



Final Product Change Notification

202008033F01

Issue Date: 02-Sep-2020

Effective Date: 30-Nov-2020

Dear *Gordon Love*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to [view this notification online](#)

This notice is NXP Company Proprietary.



QUALITY

Management Summary

Cu Wire is being added as a wirebond material option for LPC236x and LPC24xx in TFBGA100, TFBGA180 and TFBGA208 packages at assembly site NXP-ATKH.

Change Category

- | | | | | |
|--|--|---|---|---|
| ☐ Wafer Fab Process | ☐ Assembly Process | ☒ Product Marking | ☐ Test Location | ☐ Design |
| ☐ Wafer Fab Materials | ☒ Assembly Materials | ☐ Mechanical Specification | ☐ Test Process | ☐ Errata |
| ☐ Wafer Fab Location | ☐ Assembly Location | ☐ Packing/Shipping/Labeling | ☐ Test Equipment | ☐ Electrical spec./Test coverage |
| ☐ Firmware | ☐ Other | | | |

LPC236x, LPC24xx in
TFBGA100, 180, 208
Package Cu Wire
Qualification for NXP-
ATKH

Description of Change

Copper wire has been qualified and will be added as a wirebond material. Upon effective date, NXP will begin shipping product with copper wire.

Mold compound has been upgraded to support copper wire.

See attached Self Qualification Report (SQR) for details of the reliability qualification test results.

Samples of the following part numbers will be available:

LPC2368FET100

LPC2458FET180

LPC2460FET208

LPC2468FET208

LPC2470FET208

Reason for Change

Adding Copper wire is for supply assurance.

Identification of Affected Products

Top side marking

Product version is incremented from "D" to "E". See marking details in attached Self Qualification Report (SQR) document.

Product Availability

Sample Information

Samples are available from 14-Aug-2020

Production

Planned first shipment 28-Nov-2020

Anticipated Impact on Form, Fit, Function, Reliability or Quality

The top side marking, wire composition and mold compound are the only changes. No Impact to fit, function or reliability.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Self qualification: [view online](#)



Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 02-Oct-2020.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Tim Camenzind

Position Quality Manager - LPC Microcontroller Products

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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